APPLICA	BLE	STAN	DARD									
Operating temperature ra			ange	-55 °C to 85 °C range		e temperature			-10°C TO 50°C(Packed condition)			
RATING	Volt	tage					Operating or storage humidity range		Relative humidity 90 % MAX (Not			ewed
Current						Applica	plicable cable		t=0.3±0.03mm, Gold plating			g
				SPEC	IFIC	OITA	NS					
П	ГЕМ			TEST METHOD				R	EQU	IREMENTS	QT	АТ
CONSTR	RUC	TION										
General exa	mina	tion	Visually and by measuring instrument.				According to drawing. (note 1)				×	×
Marking				d visually.			(note	1)			×	×
		L CHA		RISTICS								_
Voltage proof			90 V AC for 1 min.				No flashover or breakdown.				×	-
Insulation re	sistai	nce	100 V DC.				50 MΩ MIN.				×	-
Contact resi	stanc	е	AC 20 mV MAX , 1 mA .				100 mg	Ω MAX.			×	-
							Including FPC bulk resistance (L=8mm)					
	VIC/	AL CHA		RISTICS								
Vibration			Frequency 10 to 55 Hz, half amplitude 0.75 mm, for 10 cycles in 3 axial directions.							ontinuity of 1 µs.	×	-
Shock			981 m/s <sup>2</sup> , duration of pulse 6 ms				<ul><li>② Contact resistance: 100 mΩ MAX.</li><li>③ No damage, crack and looseness of parts.</li></ul>				×	1_
Maskari		. t	at 3 times in 3 both axial directions.									
Mechanical operation			10 times insertions and extractions.				<ol> <li>Contact resistance: 100 mΩ MAX.</li> <li>No damage, crack and looseness of parts.</li> </ol>				×	-
FPC insertion force			Measured by applicable FPC				Insertion force : Direction of insertion				×	<del> </del>
			(Thickness of FPC shall be t=0.30mm				2.6+0.14 × n N MAX ( <i>note 2</i> )					
FPC retention	n for	<u></u>	at initial condition.)  Measured by applicable FPC				(n: Number of contacts)  Retention force : Direction of extraction				<b>-</b>	
rro retention force			(Thickness of FPC shall be t=0.30mm				5+0.07 × n N MIN ( <i>note3</i> )			×	-	
				condition.)				mber of co	,	,		
				ACTERISTICS								
Corrosion sa	alt mis	st	Exposed for 96 h.	at $35\pm2$ °C, $5$ % salt water	spray		① Contact resistance: 100 mΩ MAX.				×	-
Rapid chang	ge of			ture-55→+15⊤o+35→+85→	+15то+3	35°C	<ol> <li>Contact resistance: 100 mΩ MAX.</li> </ol>				×	<del> </del> _
temperature			Time $30 \rightarrow 2 \text{ to } 3 \rightarrow 30 \rightarrow 2 \text{ to } 3 \text{ min}$				② Insulation resistance: 50 M $\Omega$ MIN.					
Down boot			Under 5 cycles.				③ No damage, crack and looseness of parts.					
Damp heat (steady state	e)		Exposed at 40±2 °C, Relative humidity 90 to 95 %, 96 h.							×	-	
Damp heat,			Exposed at -10 to +65 °c,			① Contact resistance: 100 mΩ MAX.				×	_	
			Relative humidity 90 to 96 %, 10 cycles, TOTAL 240 h.				② Insulation resistance: 1 MΩ MIN.					
			To cycles, TOTAL 240 II.				(At high humidity)  ③ Insulation resistance: 50 MΩ MIN.					
							(At dry)					
							④ No damage, crack and looseness of parts					
COUN	IT	DE	SCRIPTION	ON OF REVISIONS		DESIG	NED			CHECKED		ATE
3	DIS-		DIS-	DIS-F-00010250		SE. YOKO	YAMA		HY. YAMAZAKI			10713
REMARK								APPROVED NF. MIYAZAKI			70404	
							DESIGN			YN. TAKASHITA		70404
Liplace otherwise enecified refer to IEC 00540								HH. MURAKAMI		70404		
Unless otherwise specified, refer to IEC 60512.							HH. MURAKAMI	I .	70404 •			
Note QT:Qualification Test AT:Assurance Test X:Applicable Test					DRAWING NO		ELC-368163-10			l		
<b>HS</b>				DATION SHEET		PART NO.				· ·		
		HIR	OSE ELECTRIC CO., LTD.			CODE	NO.	o. CL580		CL580	<u> </u>	1/2
ODM HDOO11												

	SPECIFICAT	ONS		
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ
Dry heat	Exposed at 85±2°C, 96 h.	① Contact resistance: 100 mΩ MAX.	×	_
Cold	Exposed at -55±3°C, 96 h.	② No damage, crack and looseness of parts	×	_
Sulphur dioxide [JIS C 60068-2-42]	Exposed at 40±2 °C, Relative humidity 80±5% 25±5 ppm for 96 h.	① Contact resistance: 100 m $\Omega$ MAX.	×	_
Hydrogen sulphide [JIS C 60068-2-43]	Exposed at $40\pm2$ °C, Relative humidity $80\pm5\%$ , 10 to 15 ppm for 96 h.		×	_
Solderability	Soldered at solder temperature, 245±3°C for immersion duration,3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	_
Resistance to soldering heat	1) Reflow soldering: Peak TMP. 250 °C MAX. Reflow TMP. over 220 °C 60 to 90 sec. Number of reflow: 2 times 2) Soldering irons: TMP. 350±10 °C for 5±1 sec.	No deformation of case of excessive looseness of the terminals. (note 4)	×	_

## (note 1)

This product features top-contact point.

"One Action Lock" completes FPC lock just by inserting the FPC.

Do not operate the locking-lever when inserting the FPC.

## (note 2)

Do not insert the FPC to this product at an angle.

## (note 3)



There's a case which FPC retention force doesn't fulfill the value, because FPC specification affects the result of FPC retention force.

Stabilize the FPC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC.

## (note 4)

Blisters which may be generated on the housing do not affect product performance.

Note QT:Q	ualification Test AT:Assurance Test X:Applicable Test	DRAWIN	NG NO.	ELC-368163-10-01		
HS.	SPECIFICATION SHEET	PART NO.	FH62-**S-0. 25SHW(10)			
	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	◬	2/2